

FlexRAM

Toward an Advanced Intelligent Memory System

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Rationale

- Large & increasing speed gap \Rightarrow bottleneck for many apps.
- Latency hiding bandwidth regaining techniques: diminishing returns
 - out of order
 - lockup free
 - large cache, deep hierarchies
- P/M integration: latency, bandwidth

Technological Landscape

- Merged Logic and DRAM (MLD):
 - IBM, Mitsubishi, Samsung, Toshiba and others
- Powerful: e.g. IBM SA-27E ASIC (Feb 99)
 - 0.18 μm (chips for 1 Gbit DRAM)
 - Logic frequency: 400 MHz
 - IBM PowerPC 603 proc + 16 KB I, D caches = 3%
 - Further advances in the horizon
- Opportunity: How to exploit MLD best?

Key Applications

- Data Mining (decision trees and neural networks)
- Computational Biology (protein sequence matching)
- Multimedia (MPEG-2 Encoder)
- Decision Support Systems (TPC-D)
- Speech Recognition
- Financial Modeling (stock options, derivatives)
- Molecular Dynamics (short-range forces)

Example App: Protein Matching



- Problem: Find areas of database protein chains that match (modulo some mutations) the sample protein chains

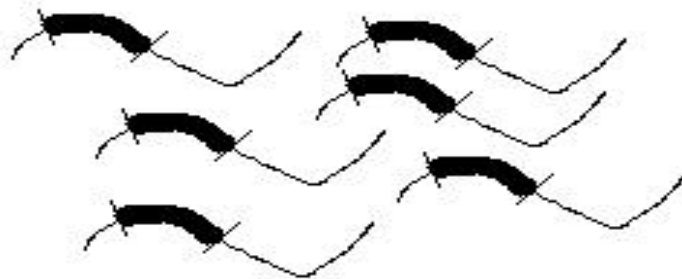
How the Algorithm Works

- Pick 4 consecutive amino acids from sample



GDSL

- Generate most-likely mutations



GDSI

GDSM

ADSI

AESI

AETI

GETM

Example App: Protein Matching

- Compare them to every positions in the database proteins



- If match is found: try to extend it



How to Use MLD

- Main compute engine of the machine
 - Add a traditional processor to DRAM chip \Rightarrow Incremental gains
 - Include a special (vector/multi) processor \Rightarrow Hard to program

UC Berkeley: IRAM

Notre Dame: Execube, Petaflops

MIT: Raw

Stanford: Smart Memories

How to Use MLD (II)

- Co-processor, special-purpose processor
 - ATM switch controller
 - Process data beside the disk
 - Graphics accelerator

Stanford: Imagine

UC Berkeley: ISTORE

How to Use MLD (III)

- Our approach: replace memory chips
 - PIM chip processes the memory-intensive parts of the program

Illinois: FlexRAM

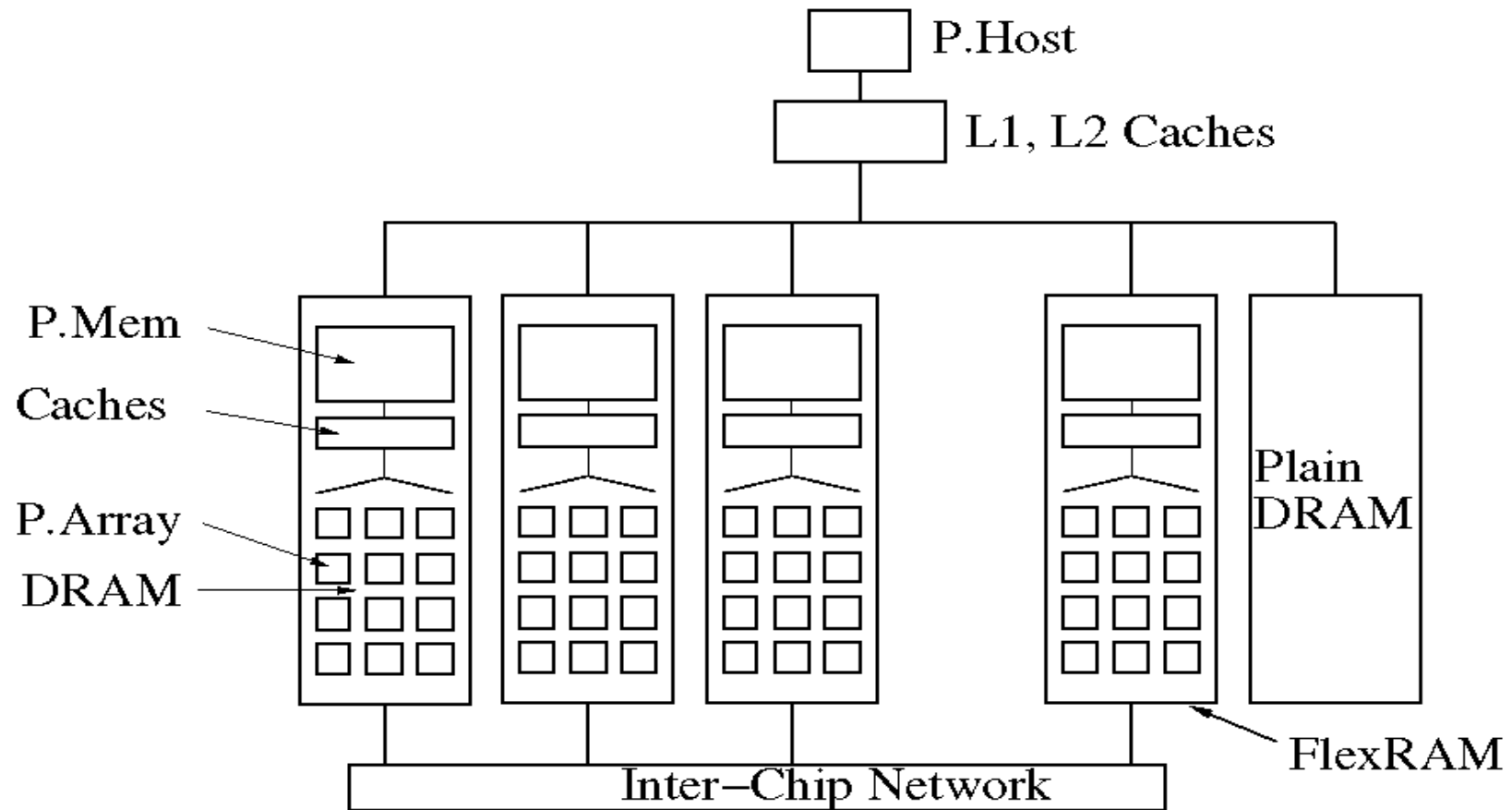
UC Davis: Active Pages

USC-ISI: DIVA

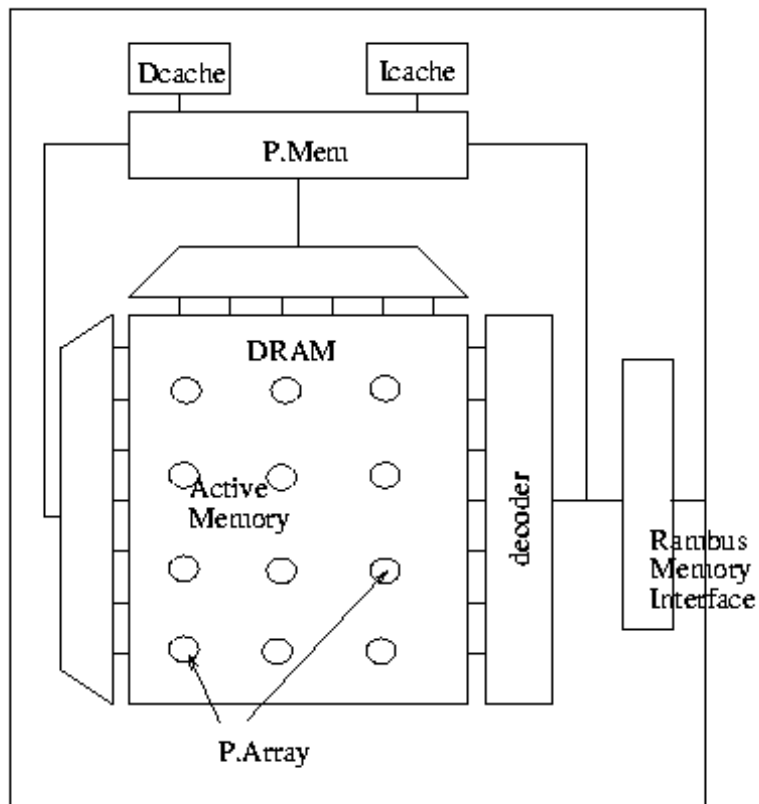
Our Solution: Principles

- Extract high bandwidth from DRAM:
 - Many simple processing units
- Run legacy codes with high performance:
 - Do not replace off-the-shelf μ P in workstation
 - Take place of memory chip. Same interface as DRAM
 - Intelligent memory defaults to plain DRAM
- Small increase in cost over DRAM:
 - Simple processing units, still dense
- General purpose:
 - Do not hardwire any algorithm. No Special purpose

Architecture Proposed

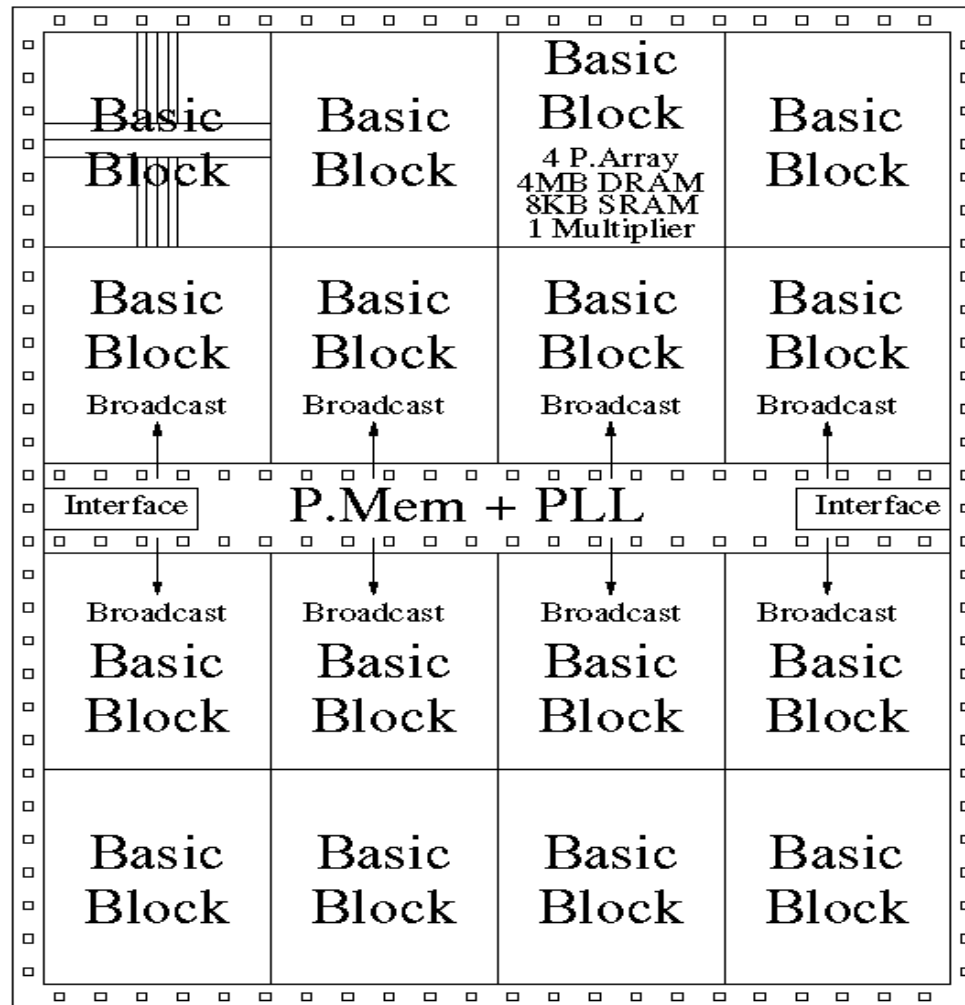


Chip Organization



- Organized in 64 1-Mbyte banks
- Each bank:
 - Associated to 1 P.Array
 - 1 single port
 - 2 row buffers (2KB)
- P.Array access: 10ns (RB hit)
20ns (miss)
- On-chip memory b/w 102GB/s

Chip Layout



Basic Block

1 MB DRAM Block	8 KB I-Memory (4-Port SRAM)	Multiplier + DLL	1 MB DRAM Block
Memory Control Block			Memory Control Block
P.Array			P.Array
P.Array			P.Array
Memory Control Block			Memory Control Block
1 MB DRAM Block			1 MB DRAM Block

P Array

- 64 P.Arrays per chip. Not SIMD but SPMD
- 32-bit integer arithmetic; 16 registers
- No caches, no floating point
- 4 P.Arrays share one multiplier
- 28 different 16-bit instructions
- Can access own 1 MB of DRAM plus DRAM of left and right neighbors. Connection forms a ring
- Broadcast and notify primitives: Barrier

Instruction Memory

- Group of 4 P.Arrays share one 8-Kbyte, 4-ported SRAM instruction memory (not I-cache)
 - Holds the P.Array code
 - Small because short code
 - Aggressive access time: 1 cycle = 2.5 ns

P Mem

- 2-issue in-order: PowerPC 603 16KB I,D caches
- Executes serial sections
- Communication with P.Arrays:
 - Broadcast/notify or plain write/read to memory
 - Communication with other P.Mems:
- Memory in all chips is visible
- Access via the inter-chip network
- Must flush caches to ensure data coherence

Area Estimation (mm²)

PowerPC 603+caches:	12
64 Mbytes of DRAM:	330
SRAM instruction memory:	34
P.Arrays:	96
Multipliers:	10
Rambus interface:	3.4
Pads + network interf. + refresh logic	20

Total = 505

Of which 28% logic, 65% DRAM, 7% SRAM

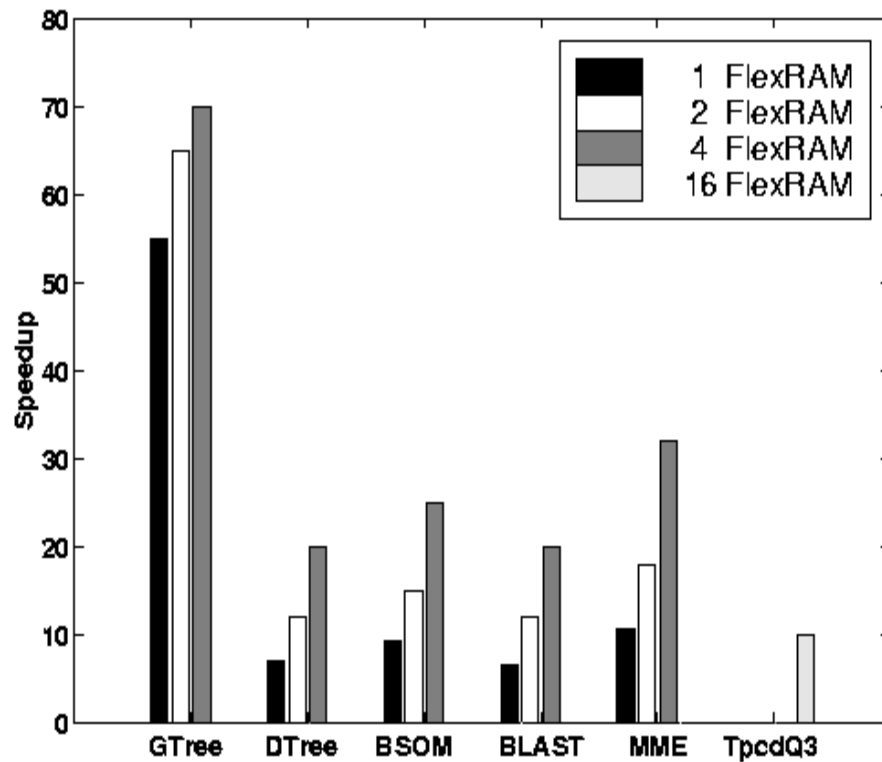
Issues

- **Communication P.Mem-P.Host:**
 - P.Mem cannot be the master of bus
 - Protocol intensive interface: Rambus
- **Virtual memory:**
 - P.Mems and P.Arrays use virtual addresses
 - Small TLB for P.Arrays
 - Special page mapping

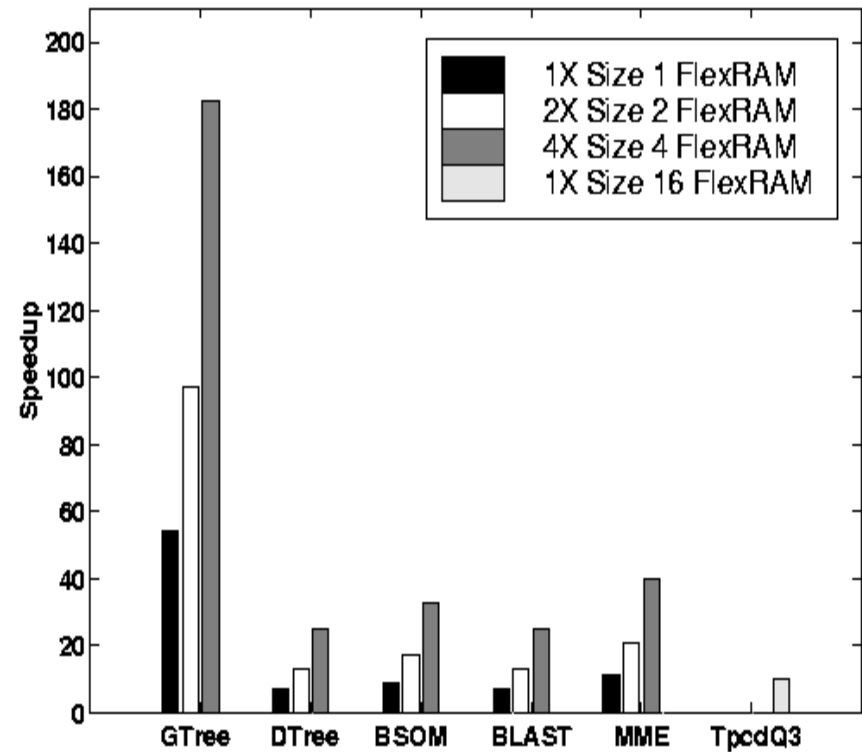
Evaluation

P.Host	P.Host L1 & L2	Bus & Memory	
Freq: 800 MHz	L1 Size: 32 KB	Bus: Split Trans	
Issue Width: 6	L1 RT: 2.5 ns	Bus Width: 16 B	
Dyn Issue: Yes	L1 Assoc: 2	Bus Freq: 100 MHz	
I-Window Size: 96	L1 Line: 64 B	Mem RT: 262.5 ns	
Ld/St Units: 2	L2 Size: 256 KB		
Int Units: 6	L2 RT: 12.5 ns		
FP Units: 4	L2 Assoc: 4		
Pending Ld/St: 8/8	L2 Line: 64 B		
BR Penalty: 4 cyc			
P.Mem	P.Mem L1	P.Array	
Freq: 400 MHz	L1 Size: 16 KB	Freq: 400 MHz	
Issue Width: 2	L1 RT: 2.5 ns	Issue Width: 1	
Dyn Issue: No	L1 Assoc: 2	Dyn Issue: No	
Ld/St Units: 2	L1 Line: 32 B	Pending St: 1	
Int Units: 2	L2 Cache: No	Row Buffers: 3	
FP Units: 2		RB Size: 2 KB	
Pending Ld/St: 8/8		RB Hit: 10 ns	
BR Penalty: 2 cyc		RB Miss: 20 ns	

Speedups

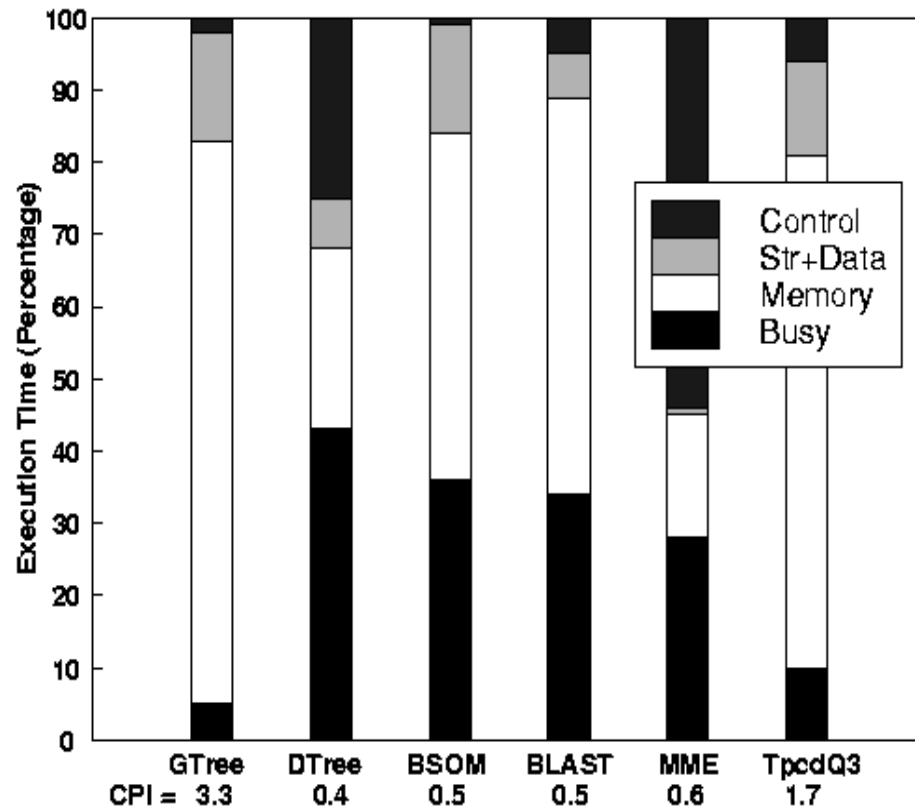


■ Constant Problem Size



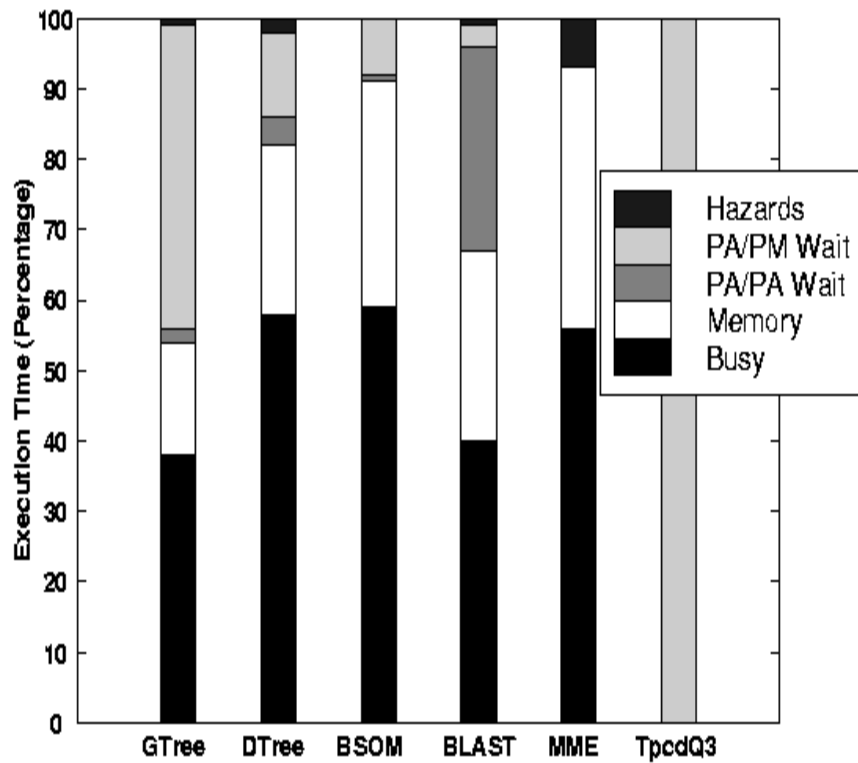
■ Scaled Problem Size

Utilization

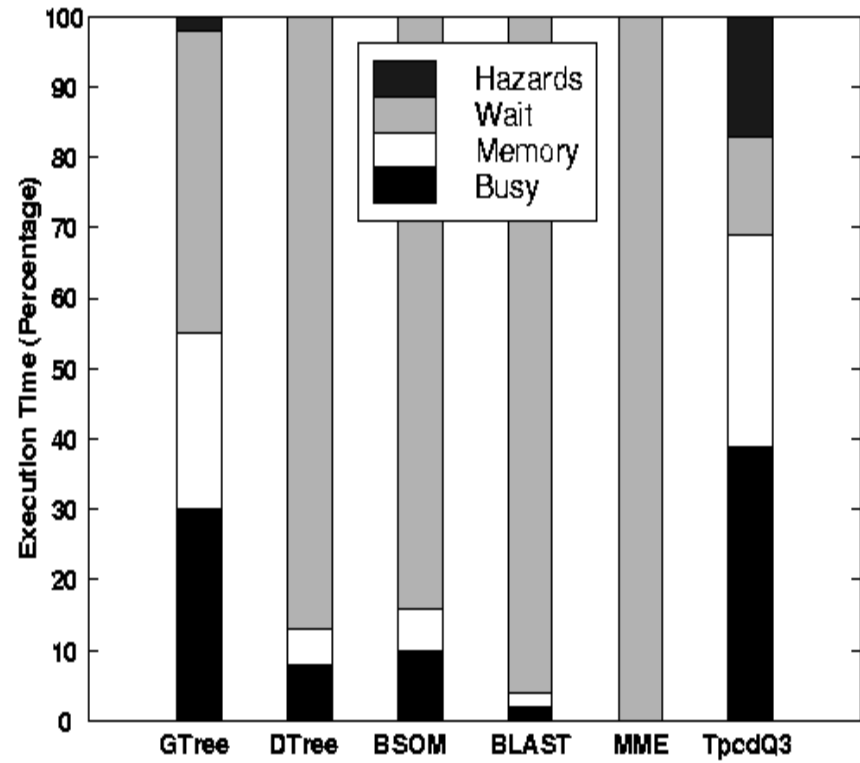


■ Low P.Host Utilization

Utilization

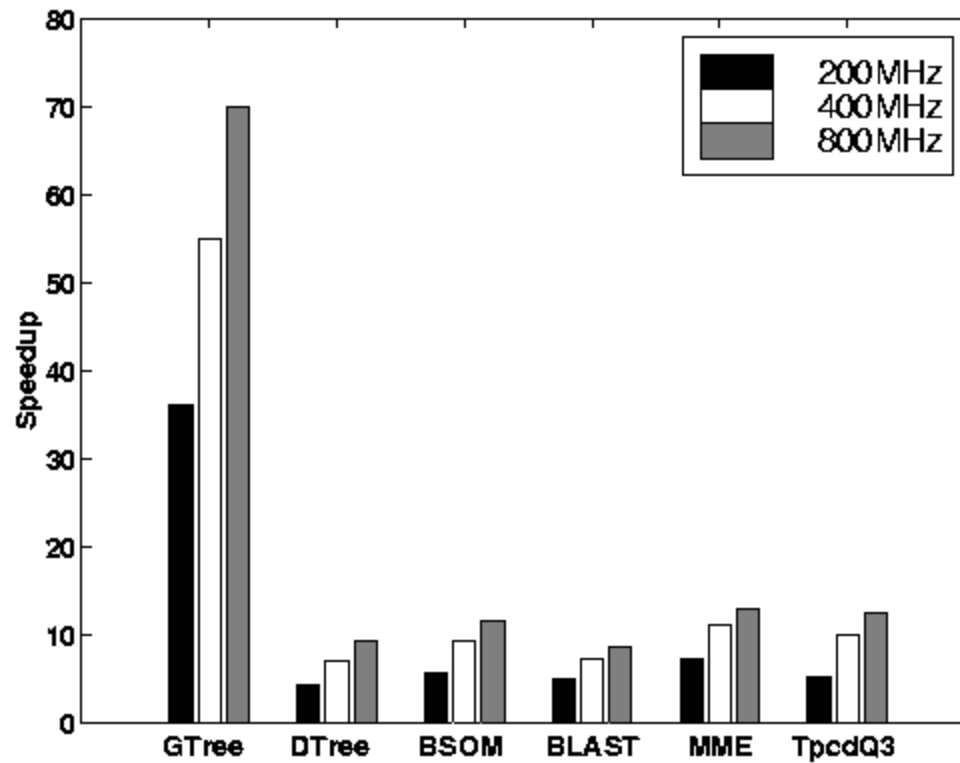


■ High P.Array Utilization



■ Low P.Mem Utilization

Speedups



■ Varying Logic Frequency

Problems & Future Work

- Fabrication technology
 - heat, power dissipation,
 - effect of logic noise on memory,
 - package, yield, cost
- Fault tolerance
 - defect memory bank, processor
- Compiler, Programming Language.

Conclusion

- We have a handle on:
 - A promising technology (MLD)
 - Key applications of industrial interest
- Real chance to transform the computing landscape

Communication Pmem \Rightarrow PHost

■ **Communication P.Mem-P.Host:**

- P.Mem cannot be the master of bus
- P.Host starts P.Mems by writing register in Rambus interface.
- P.Host polls a register in Rambus interface of master P.Mem
- If P.Mem not finished: memory controller retries. Retries are invisible to P.Host

Virtual Address Translation

VPN	PPN	length
200	1	50
400	51	100

204

5

